AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently amended) A semiconductor device comprising:

a plurality of semiconductor chips layered on a circuit substrate, wherein:

at least two ~~three of the plurality of~~ semiconductor chips are respectively a first semiconductor chip, and a second semiconductor chip, ~~and a third semiconductor chip,~~ each of which has a circuit formation surface and a reverse surface with respect to the circuit formation surface,

the first semiconductor chip being mounted on the circuit substrate ~~or the third semiconductor chip~~ in such a manner that the reverse surface of the first semiconductor chip faces the circuit substrate,

the second semiconductor chip (i) being mounted on the first semiconductor chip in such a manner that the reverse surface of the second semiconductor chip faces the circuit formation surface of the first semiconductor chip, and (ii) having protruded part formed by protruding at least one outer edge of the second semiconductor chip from an outer edge of the first semiconductor chip as viewed from above,

the first semiconductor chip and the second semiconductor chip being wire-bonded ~~wire-boned~~ with the circuit substrate;

the semiconductor device comprising a mounting-use bonding layer on the reverse surface of the second semiconductor chip, ~~and~~

the mounting-use bonding layer functioning as a bonding agent for mounting the second semiconductor chip on the first semiconductor chip, and filling a gap between (i) the circuit

substrate ~~or a third semiconductor chip,~~ and (ii) the protruded part of second semiconductor chip; and

wherein a surface of the mounting-use bonding layer has the same shape as the reverse surface of the second semiconductor chip, the surface being in touch with the reverse surface of the second semiconductor chip.

2-4. (Canceled)

5. (Withdrawn) The semiconductor device as set forth in claim 1, wherein:

the mounting-use bonding layer forms, in the gap, a supporting member for supporting the protruded part; and

a surface of the supporting member has the same shape as the reverse surface of the protruded part, the surface being in contact with the reverse surface of the protruded part.

6. (Canceled)

7. (Original) The semiconductor device as set forth in claim 1, wherein:

the mounting-use bonding layer is made of a thermosetting resin being in a solid state at ordinary temperatures, being melted into a liquid state by heating, and being solidified by heat treatment after being melted.

8. (Canceled)

9. (Original) The semiconductor device as set forth in claim 1, wherein: the mounting-use bonding layer is made of an epoxy resin.

10. (Canceled)

11. (Withdrawn) The semiconductor device as set forth in claim 1 wherein: the mounting-use bonding layer includes two layers, one of which is associated with the second semiconductor chip and is less meltable into a liquid state than the other one of the two layers, which is associated with the first semiconductor chip.

12. (Canceled)

13. (Original) The semiconductor device as set forth in claim 1, wherein: the mounting-use bonding layer is made of a liquid resin.

14-16. (Canceled)

17. (New) The semiconductor device of claim 1, wherein a third semiconductor chip is provided between the substrate and the first semiconductor chip.